

APAC Innovation Summit 2015 Series - Robotics

Connect • Collaborate • Catalyse

24-25 June 2015

Grand Hall, Hong Kong Science Park

Featured Speakers



Gordon Cheng
Technische Universität
München



Dario Floreano
Ecole Polytechnique Fédérale
de Lausanne



Homayoon Kazerooni
University of California,
Berkeley



Kay Matzner
Fraunhofer IFF



Marc Papageorge
Spec Sensors



Robert Riener
Eidgenössische Technische
Hochschule Zürich

Note: Information is subject to change without prior notice.

A perfect platform for you to be inspired and to network with industry partners for collaboration opportunities!

Register now and get an early bird* 20% discount.

* Early bird offer until 31 May 2015



Registration and programme details
www.apacinnosummit.net

亞太創新峰會 2015 系列 - 機械技術

連繫 • 協作 • 促進

2015 年 6 月 24 - 25 日

香港科學園展覽廳

主講嘉賓



Gordon Cheng
Technische Universität
München



Dario Floreano
Ecole Polytechnique Fédérale
de Lausanne



Homayoon Kazerooni
University of California,
Berkeley



Kay Matzner
Fraunhofer IFF



Marc Papageorge
Spec Sensors



Robert Riener
Eidgenössische Technische
Hochschule Zürich

注意: 資料如有更改, 恕不另行通知。

這匯聚來自全球學術界、研究領域和業界的平台能助你聯繫、促進協作、推動新思維及發展, 切勿錯過!

請即報名以享八折票價優惠*!

*優惠適用於即日起至 2015 年 5 月 31 日。



報名及活動詳情

www.apacinnosummit.net

APAC Innovation Summit 2015 Series - Robotics

Connect • Collaborate • Catalyse

24-25 June 2015

Grand Hall, Hong Kong Science Park

亞太創新峰會 2015 系列 - 機械技術

連繫 • 協作 • 促進

2015 年 6 月 24 - 25 日

香港科學園展覽廳



www.apacinnosummit.net



Event listing

APAC Innovation Summit 2015 Series - Robotics

Connect • Collaborate • Catalyse

With an aim to connect all stakeholders, facilitate collaboration and catalyse new ideas and opportunities, APAC Innovation Summit, the flagship event of Hong Kong Science and Technology Parks Corporation, adopts a thematic approach covering 5 major technology areas with a series of events spreading over Year 2015-2016. The upcoming "Robotics" series in June will gather a panel of world-renowned experts to share on the robotics technology trend and its applications in homecare, edutainment, industrial automation and medical field. The 2-day event will also feature a mini-exhibition to showcase the latest innovations from academia, research community and industry.

Date: 24 - 25 June 2015
Time: 09:30 – 17:30
Venue: Grand Hall, Hong Kong Science Park
Organiser: Hong Kong Science and Technology Parks Corporation
Website: <http://www.apacinnosummit.net/>
Enquiry: +852-26296840/ info@apacinnosummit.net

亞太創新峰會 2015 系列 - 機械技術

連繫 • 協作 • 促進

日期: 2015 年 6 月 24 - 25 日
時間: 09:30 – 17:30
地點: 香港科學園展覽廳
主辦單位: 香港科技園公司
網頁: <http://www.apacinnosummit.net/>
查詢: +852-26296840/ info@apacinnosummit.net